NPN Silicon Epitaxial Planar Power Transistor

Low Frequency Transistor



1.Base 2.Collector 3.Emitter SOT-89 Plastic Package

Parameter	Symbol	Value	Unit
Collector Base Voltage	Vсво	60	V
Collector Emitter Voltage	VCEO	50	V
Emitter Base Voltage	VEBO	6	V
Collector Current - DC Collector Current - Pulse (t _P =10 ms)	Ic Icp	3 6	A A
Total Power Dissipation	P _{tot}	0.5 ¹⁾ 2 ²⁾	W
Junction Temperature	Tj	150	°C
Storage Temperature Range	T _{stg}	- 55 to + 150	°C

Absolute Maximum Ratings (T_a = 25°C)

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient	Reja	250 ¹⁾ 62.5 ²⁾	°C/W

¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. ²⁾ When mounted on a 40 X 40 X 0.7 mm ceramic board.



Characteristics at Ta = 25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit
DC Current Gain at $V_{CE} = 2 V$, $I_C = 0.5 A$ at $V_{CE} = 2 V$, $I_C = 1.5 A$	h _{FE} h _{FE}	82 45	-	270 -	-
Collector Base Cutoff Current at V_{CB} = 60 V	I _{CBO}	-	-	0.1	μA
Emitter Base Cutoff Current at $V_{EB} = 5 V$	I _{EBO}	-	-	0.1	μA
Collector Base Breakdown Voltage at I_c = 50 μ A	V _{(BR)CBO}	60	-	-	V
Collector Emitter Breakdown Voltage at I_c = 1 mA	V _{(BR)CEO}	50	-	-	V
Emitter Base Breakdown Voltage at I _E = 50 μA	V _{(BR)EBO}	6	-	-	V
Collector Emitter Saturation Voltage at $I_c = 1 A$, $I_B = 50 mA$	V _{CE(sat)}	-	-	0.35	V
Transition Frequency at V _{CE} = 5 V, I _C = 0.5 A, f = 100 MHz	fT	-	210	-	MHz
Collector Output Capacitance at V_{CB} = 10 V, f = 1 MHz	C _{ob}	-	25	-	pF



Electrical Characteristics Curves

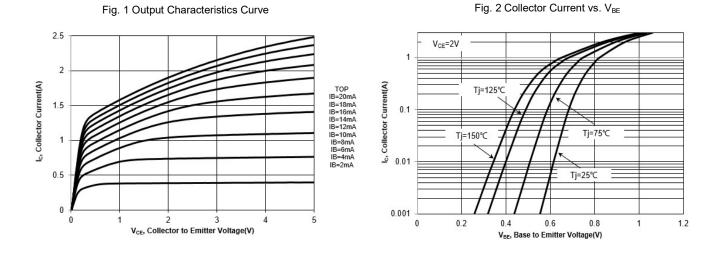
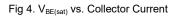
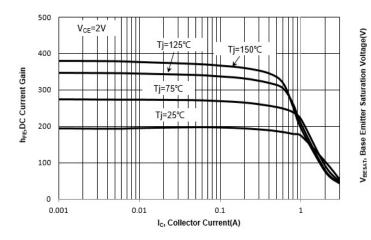


Fig 3. DC Current Gain vs. Collector Current





ттт $I_{C}/I_{B} = 20$ 1 Tj=25℃ Ti=75°C HN N Tj=150℃ Tj=125℃ ÍШ 0.1 0.001 0.01 0.1 1 Ic, Collector Current(A)



Electrical Characteristics Curves

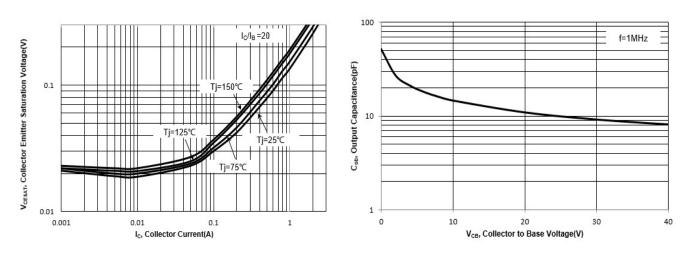
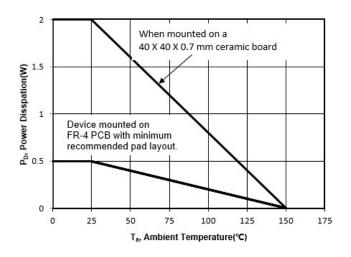


Fig. 5 VCESAT vs. Collector Current

Fig. 6 Output Capacitance

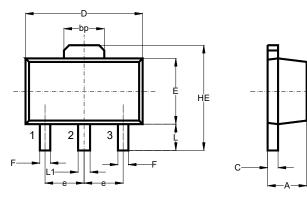
Fig. 7 Power Derating Curve





Package Outline (Dimensions in mm)

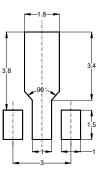






Unit	А	bp	С	D	E	F	HE	е	L	L1
22.22	1.6	1.60	0.5	4.6	2.6	0.45	4.25	1.5	1.05	0.51
mm	1.4	1.50	0.3	4.4	2.4	0.35	3.75	typ.	0.95	0.41

Recommended Soldering Footprint



Packing information

	Tape Width	Pit	tch	Ree	el Size	
Package	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity
007.00	10	0.04	0.045 + 0.004	178	7	1,000
SOT-89	12	8 ± 0.1	0.315 ± 0.004	330	13	4,000

Marking information

" 2SC4672U " = Part No.	\square
"YM" = Date Code Marking	X
"Y" = Year	2SC4672U
"M" = Month	
Font type: Arial	

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